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| --- |
| **PLEASE PROVIDE THE FOLLOWING INFORMATION:** |
| ASSEMBLY #: |       | ASSEMBLY NAME: |       |
| ASSY REV: |       | PCB REV: |       |
| CONTACT NAME: |       | PHONE #: |       |
| ACCOUNTS PAYABLE NAME: |       | ACCOUNTS PAYABLE EMAIL: |       |
|  |
| EXPECTED COMPLETION DATE OR TURN TIME (TURN TIME IS AFTER ALL MATERIALS ARE IN HOUSE): |
| DUE DATE: | CHOOSE DATE | TURN TIME: |       |
| QTY(S) REQUESTED: |       |
| IF MULTIPLE RELEASES, PLEASE SPECIFY DATES AND QUANTITIES NEEDED: |       |
| FORECAST: |  |
| ***GENERAL REWORK DETAILS*** |
| SOLDER TYPE: |  |
| TYPE OF REWORK TO BE PERFORMED: (CHECK ALL THAT APPLY) |
| **[ ]  SMT →** | [ ]  BGA REMOVAL | [ ]  BGA PLACEMENT | [ ]  BGA REMOVE & REPLACE | [ ]  PASSIVE REMOVAL |
| [ ]  PASSIVE PLACEMENT | [ ]  PASSIVE REMOVE & REPLACE | [ ]  OTHER: |       |
| **[ ]  TH →** | [ ]  PART REMOVAL | [ ]  PART INSTALLATION | [ ]  TRACE CUTS & JUMPS | [ ]  WIRE MODS |
| IF WIRE MODS ARE PRESENT IS CST APPROVED TO USE OUR STANDARD WIRE?  |  |
| IF NO, ENTER WIRE GAUGE AND COLOR: | GAUGE (AWG): |       | COLOR: |       |
| IF PARTS ARE REMOVED ARE WE TO RETURN OR SCRAP THEM?  |  |
| WILL A FIRST ARTICLE NEED TO BE SENT FOR APPROVAL PRIOR TO COMPLETING THE FULL QUANTITY? |  |
| ***THERMAL PROFILE*** |
| PROFILE BOARD PROVIDED? |  | IF SO, HOW MANY? |       |
| PROFILE REQUIRES CUSTOMER APPROVAL? |  | PROFILE PARTS PROVIDED? |  |
| ***NOTE: IF A PROFILE BOARD CANNOT BE PROVIDED CUSTOMER MUST ACCEPT THIS POTENTIAL IMPACT ON QUALITY.*** |
| MAXIMUM ALLOWED HEAT CYCLES (BGA REQUIRES 2 HEAT CYCLES PER LOCATION): |       |
| ***COMPONENT(S) – GERBERS & BOM ARE PREFERRED FOR DOCUMENTATION*** |
| COMPONENT DATASHEET PROVIDED? |  |
| PLEASE PROVIDE A LIST FOR THE FOLLOWING ITEMS:  |
| MANUFACTURER’S PART NUMBERS | QUANTITY OF PARTS PROVIDED/NEEDED | REFERENCE DESIGNATORS |
| COMPONENT TYPES: | [ ]  BGA | [ ]  MICRO-BGA | [ ]  QFN | [ ]  OTHER: |       |
| COMPONENT PITCH: |  | COMPONENT CONDITION: |  |
| COMPONENT MOISTURE SENSITIVITY LEVEL (MSL): |  |
| HAVE COMPONENTS BEEN STORED/HANDLED PER J-STD-033? *CHECK ALL TO VERIFY:* |
| [ ]  ESD MOISTURE BARRIER BAG | [ ]  BAG IS SEALED | [ ]  DESICCANT USED | [ ]  HUMIDITY INDICATOR CARD |
| IF PARTS WERE NOT STORED/HANDLED PER J-STD-033, HOW LONG WERE THEY EXPOSED TO THE ENVIRONMENT? |       |
| IF THE PARTS WERE EXPOSED/COMPROMISED IS CST TO BAKE THE PARTS? |  |
| ***MATERIALS*** |
| PCB MATERIAL: |  | IF OTHER, PLEASE SPECIFY: |       |
| PCB TG RATING: |  | IF OTHER, PLEASE SPECIFY: |       |
| PCB THICKNESS: |  | IF OTHER, PLEASE SPECIFY: |       |
| PCB SURFACE FINISH: |  | IF OTHER, PLEASE SPECIFY: |       |
| ***X-RAY*** |
| IS X-RAY REQUIRED PRIOR TO PERFORMING REWORK? |  |
| CONTACT CUSTOMER AFTER PERFORMING PRE-REWORK X-RAY? |  |
| IS X-RAY REQUIRED AFTER TO PERFORMING REWORK? |  |
| WHAT PERCENTAGE OF THE BOARDS NEED X-RAY? |  |
| ***COMMENTS/NOTES:*** |
|       |